

NSR0170HT1G

Schottky Barrier Diode

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current and are used in a wide range of dc-dc converter, clamping and protection applications in portable devices. NSR0170H in a SOD-323 small footprint package enables designers to meet the challenging task of achieving higher efficiency designs and meeting reduced board space requirements.

Features

- Very Low Forward Voltage Drop – 560 mV @ 10 mA
- Low Reverse Current – 25 nA @ 50 V V_R
- 70 mA of Continuous Forward Current
- Power Dissipation of 180 mW with Minimum Trace
- Very High Switching Speed
- Low Capacitance – CT = 2 pF
- NSVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Automotive Modules
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	70	V
Forward Current (DC)	I_F	70	mA
Non-Repetitive Peak Surge Forward Current	I_{FSM}	100	mA
ESD Rating: Human Body Model Machine Model	ESD	Class 2 Class M3	

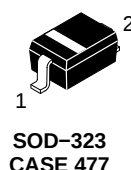
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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70 V SCHOTTKY BARRIER DIODE



MARKING DIAGRAM



Q = Specific Device Code
M = Month Code
■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NSR0170HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
NSVR0170HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR0170HT1G

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ P_D			680 180	$^\circ\text{C/W}$ mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ P_D			440 280	$^\circ\text{C/W}$ mW
Junction and Storage Temperature Range	T_J, T_{stg}			-55 to +150	$^\circ\text{C}$

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Leakage ($V_R = 50\text{ V}$) ($V_R = 70\text{ V}$)	I_R		25 -	90 3.0	nA μA
Forward Voltage ($I_F = 1.0\text{ mA}$) ($I_F = 10\text{ mA}$) ($I_F = 15\text{ mA}$)	V_F		340 560 650	390 640 730	mV
Total Capacitance ($V_R = 0\text{ V}$, $f = 1\text{ MHz}$)	C_T		2.0		pF

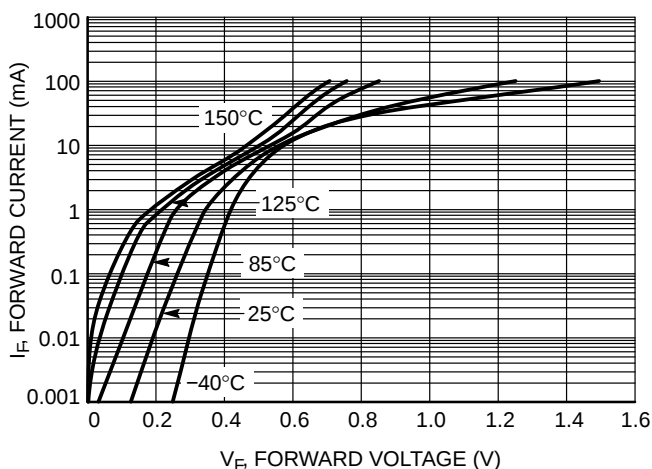


Figure 1. Forward Voltage

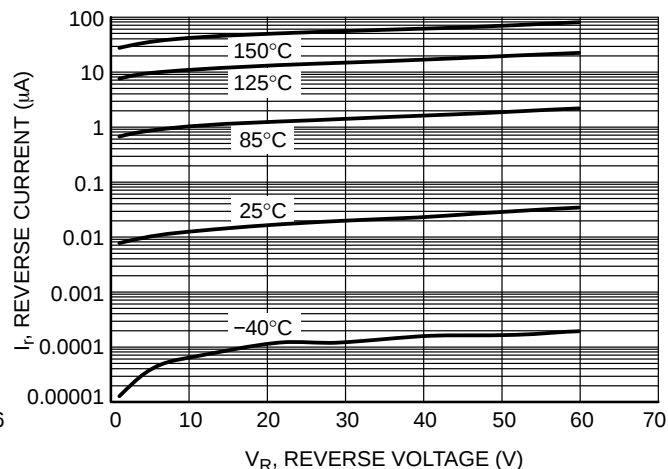


Figure 2. Leakage Current

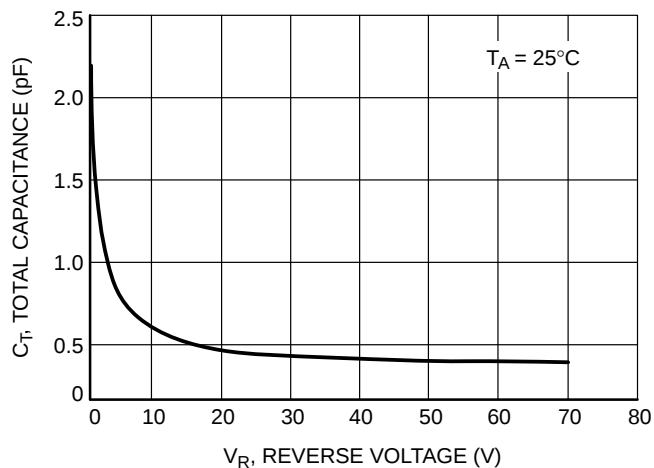
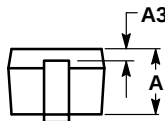
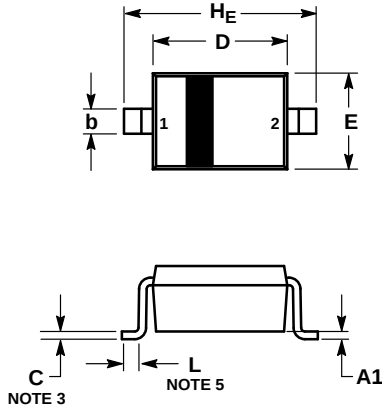


Figure 3. Total Capacitance

NSR0170HT1G

PACKAGE DIMENSIONS

SOD-323
CASE 477-02
ISSUE H

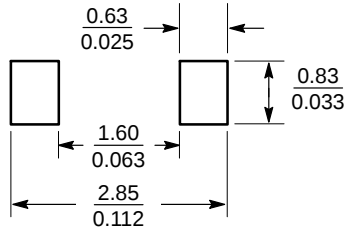


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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